Stock Code: 3467

Forcera Materials Co., Ltd.

February 20, 2025

Safe Harbor Notice

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Agenda

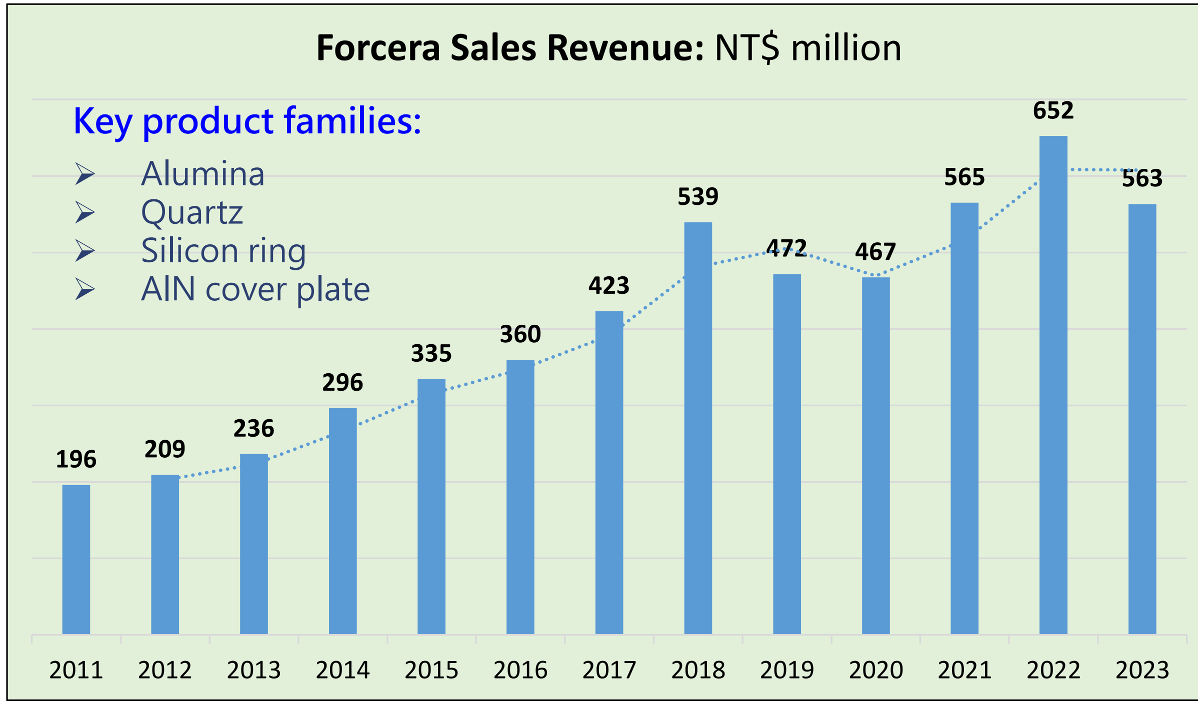
- ❑ Company profile
- ❑ Market position and part application
- ❑ External analysis and core competence
- ❑ Business performance
- ❑ Semiconductor market outlook and company strategic plans
- ❑ ESG performance

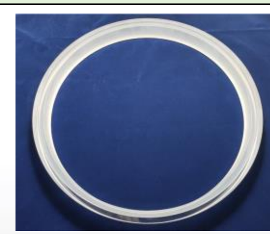
Company profile

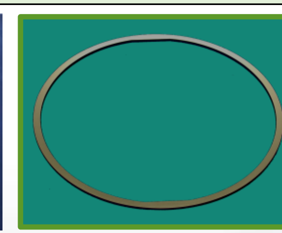
Company profile

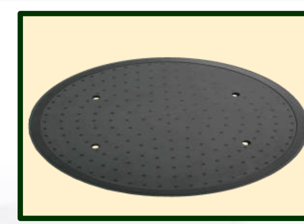
Forcera Materials Co., Ltd.

- Established: 1997
- Mfg. location: Hsinchu, Taiwan
- Capital: NT$ 282 million
- Chairman: Dr. CY Ma
- President: Starsky Wang
- No. of employees (as of Jan. '25): 188
- Business focus: semi. industry









- An OEM certified, semi grade fine ceramic chamber part solution provider with core technologies integrating from ceramic material processing through precision machining, surface treatment, and part clean & etching

Milestones

Growth through world leading equipment maker
(technical catch-up vs. first mover advantage)

Moving to leading edge node
readiness of advanced tech.

World-class competitiveness
innovative technology dev.

1990

- 2004 ISO9001:2000 certified
- 2005 **Hukou plant** construction completed and production started
- 2020 ISO 45001:2018 certified
- 2009 Company renamed as **Forcera Materials Co., Ltd**.

- 1997 Establishment of **SIC Electronics**

2000

- 2010 Qualified by the largest semi. equipment makers
- 2013 **Core technologies certified:**
  1) semi grade material **Sicalox**
  2) component **fabrication technology**
  3) **part clean technology**
- 2014 business expanded through collaboration with top semiconductor company
- 2019 **moving to leading edge nodes**

2010

- 2020 Higher purity alumina material **FA998 certified** by top semiconductor company
- 2020 Mass production of **300mm ceramic domes** commenced

2020

2021~2024

- 2021 Collaboration with world leading semiconductor company for **leading-edge, innovative technology development**
- 2024 Innovative ceramic material dev. for leading nodes process completed for product testing
- 2024 A **new, advanced part clean line construction** commenced through collaboration with world leading semiconductor equipment maker
- Dec. 4, 2024 **Listing application approved by Taipei Exchange**

Market position and part application

Market position

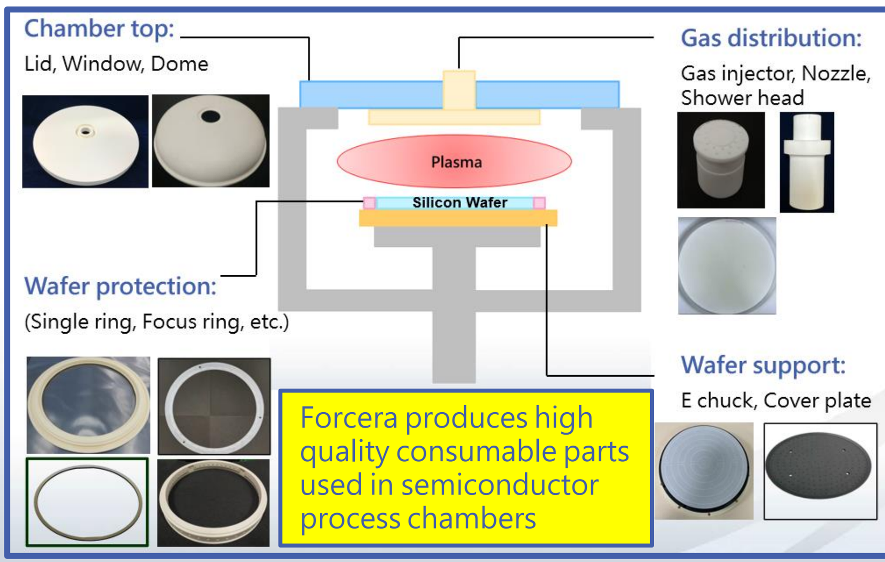
- Semiconductor Value Chain:

Upstream
- IP design /IC design OEM → IC design

Mid-stream
- IC Manufacturing (Foundry/Memory)
- Equipment
- Mask
- Chemicals

Downstream
- IC Packaging & Testing → IC
- Mfg. and Inspection Equipment
- Substrate
- Lead Frame
- IC Channel

- Front-end Process Equipment Parts:



- Semiconductor equipment supply chain:

Semiconductor equipment makers
- Lam Research (科林)
- Tokyo Electron (東京威力)
- Applied Materials (應用材料)

End users
- tsmc
- SAMSUNG
- intel

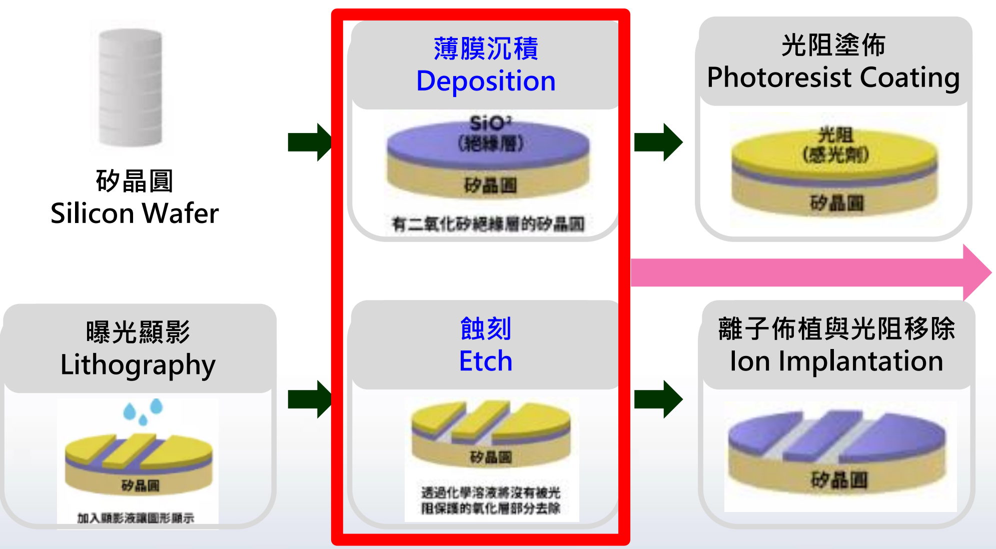
Parts application

The「invisible driving force」behind semiconductor manufacturing

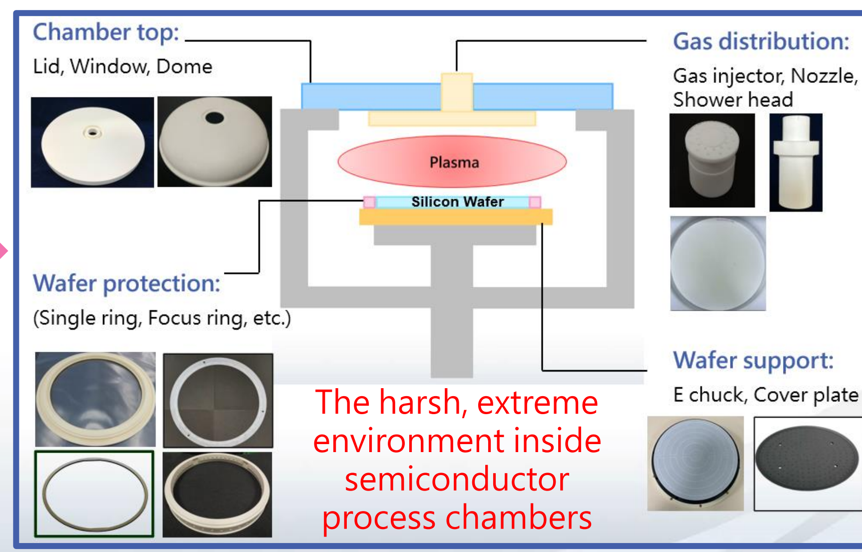
- ➢ Part quality impacts directly on the chip production yield
- ➢ The excellent material properties withstand the extreme environment in semiconductor process chambers

✓ High purity, density | ✓ Plasma resistance | ✓ High cleanliness level → ✓ Effective particle control

- **Semiconductor manufacturing process:**



- **Deposition & etch process chambers:**

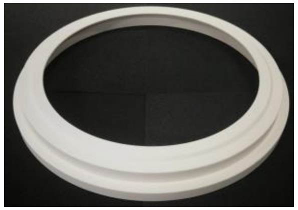


Part families

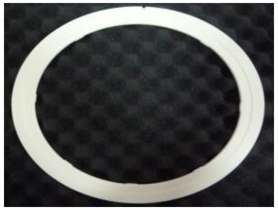
200mm domes

300mm domes

300mm Insulator



Deposition Ring

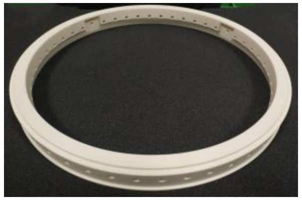


Focus Ring

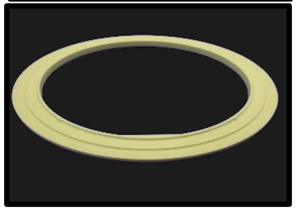
Cover Ring

Chamber Insert

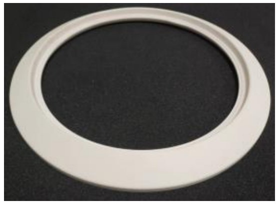
Pumping Liner



Collar Ring



Single Ring

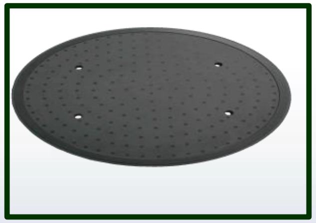


Capture Ring

Insert

Alumina (氧化鋁陶瓷)

Cover Plate

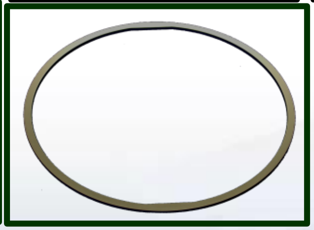


Shadow Ring

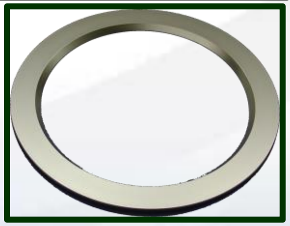
Qtz Window

Insulator

Si Insert Ring



Si Top Ring



AlN (氮化鋁)

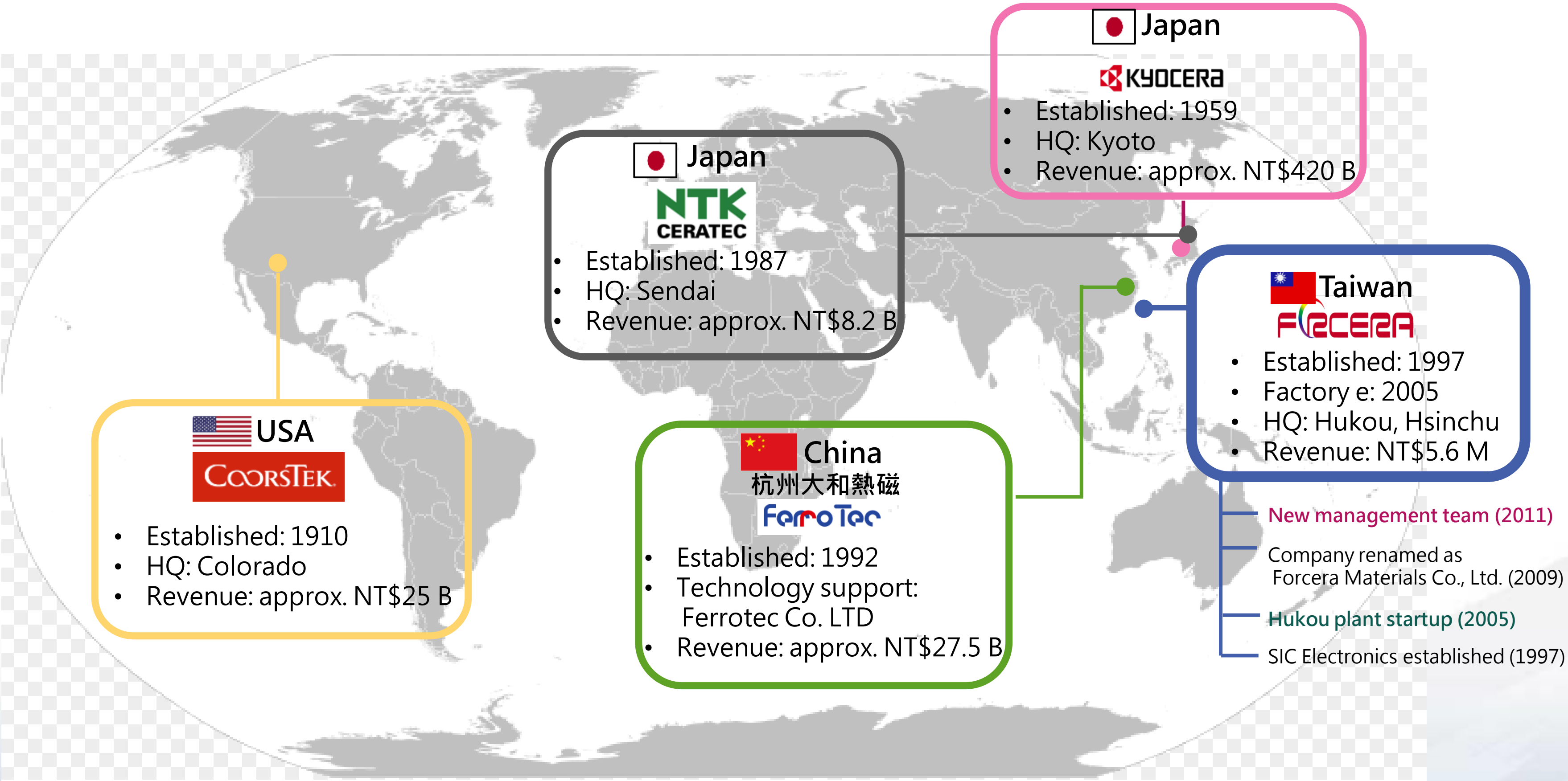
Quartz (石英)

Si Rings (矽環)

External analysis and core competence

Competitive environment: fine ceramic

- **Competitors:** long-standing market development with first-mover advantage
- **Forcera:** challenge of technical catch-up, trying to develop global competitiveness



Source: Forcera analysis based on the information published on company website

Business performance

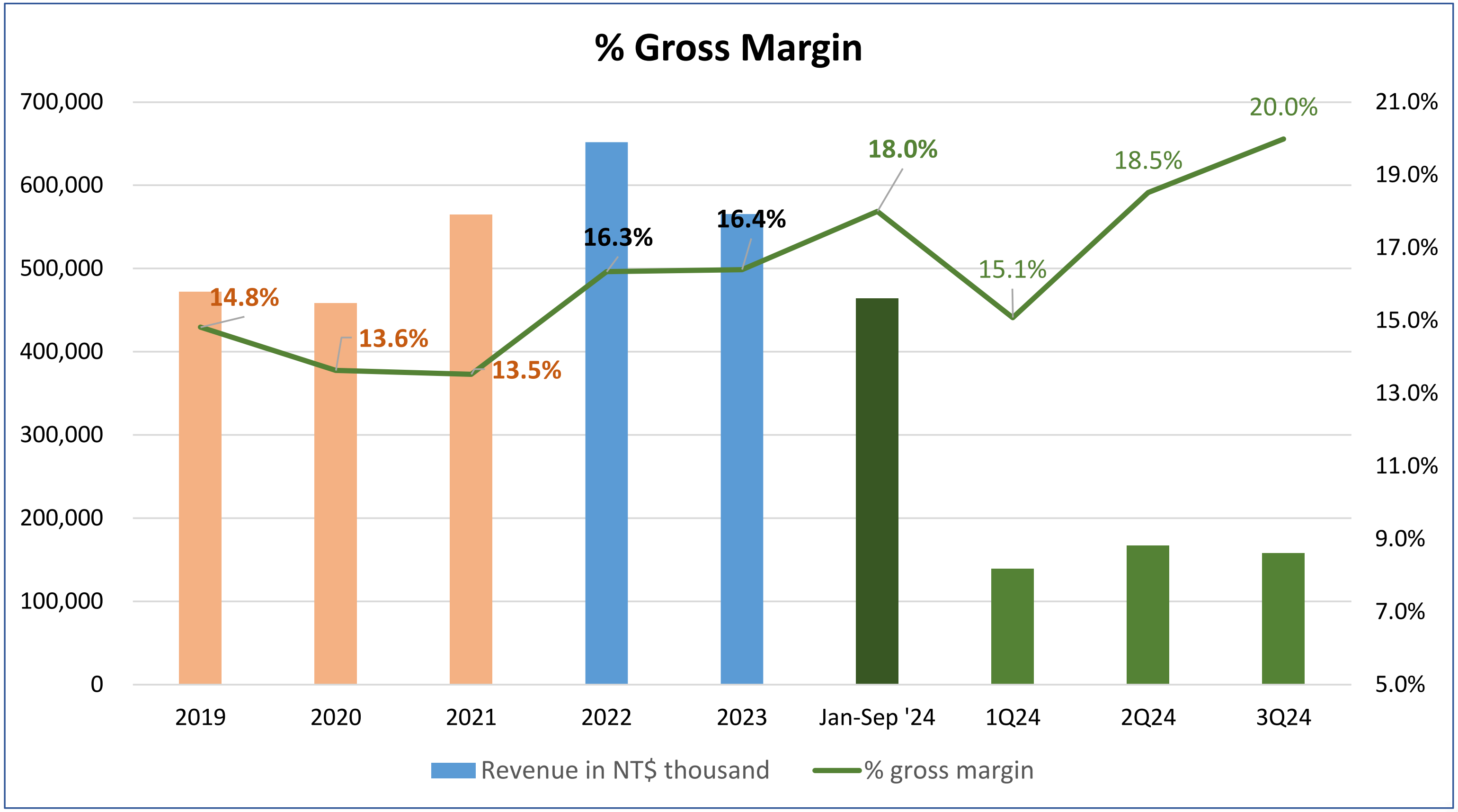
Income statement: 2021 to 2023

(NTD in thousand)	2021		2022		2023		2023 over 2022	2023 over 2021
	Audited	%	Audited	%	Audited	%		
Net Revenue	564,799	100.0%	651,728	100.0%	563,365	100.0%	-13.6%	-0.3%
COGS	488,440	86.5%	545,217	83.7%	471,248	83.6%	-13.6%	-3.5%
Gross Margin	76,359	13.5%	106,511	16.3%	92,117	16.4%	+ 0.1 ppts	+ 2.8 ppts
Operating Expenses	57,897	10.3%	72,414	11.1%	73,287	13.0%	1.2%	26.6%
Operating Income	18,462	3.3%	34,097	5.2%	18,830	3.3%	-44.8%	2.0%
Non-Operating Items	(2,630)	-0.5%	8,474	1.3%	3,674	0.7%	-56.6%	-239.7%
Income Before Tax	15,832	2.8%	42,571	6.5%	22,504	4.0%	- 2.5 ppts	+ 1.2 ppts
Net Income	15,832	2.8%	47,942	7.4%	22,176	3.9%	- 3.4 ppts	+ 1.1 ppts
EPS	0.66		2.01		0.80			

Income statement: Jan. to Sep. 2024

(NTD in thousand)	2023 1-9月		2024 1-9月		2024 Q1		2024 Q2		2024 Q3		2024 over 2023
	Audited	%	Audited	%	Audited	%	Audited	%	Audited	%	
Net Revenue	434,028	100.0%	463,609	100.0%	139,093	100.0%	166,814	100.0%	157,702	100.0%	6.8%
COGS	361,105	83.2%	380,229	82.0%	118,118	84.9%	135,926	81.5%	126,185	80.0%	5.3%
Gross Margin	72,923	16.8%	83,380	18.0%	20,975	15.1%	30,888	18.5%	31,517	20.0%	+1.2 ppts
Operating Expenses	54,891	12.6%	63,633	13.7%	19,262	13.8%	21,604	13.0%	22,766	14.4%	15.9%
Operating Income	18,032	4.2%	19,747	4.3%	1,713	1.2%	9,284	5.6%	8,751	5.5%	+0.2 ppts
Non-Operating Items	3,855	0.9%	2,983		2,190		1,028		(237)		-
Income Before Tax	21,887	5.0%	22,730	4.9%	3,904	2.8%	10,312	6.2%	8,514	5.4%	+0.1 ppts
Net Income	19,792	4.6%	20,561	4.4%	3,904	2.8%	8,853	5.3%	7,805	4.9%	-0.4 ppts
EPS	0.72		0.73		0.14		0.31		0.28		0.01

% gross margin



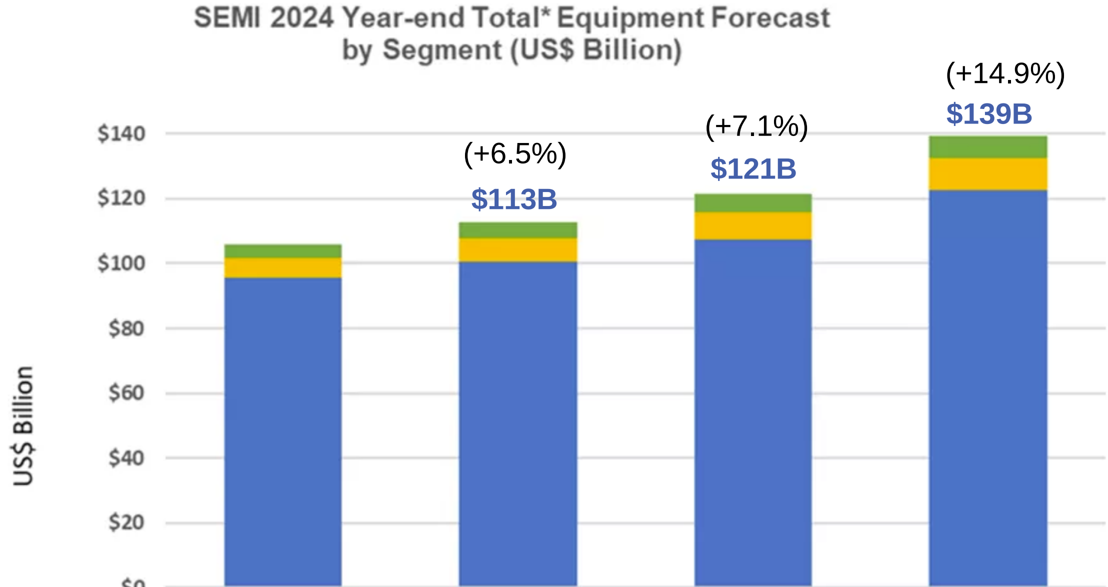
- % gross margin keeps improving through product portfolio optimization

Balance sheets & key indices

(NTD in thousand)	Sep 30, 2024		June 30, 2024		December 31, 2023		December 31, 2022		December 31, 2021	
	Amount	%	Amount	%	Amount	%	Amount	%	Amount	%
Cash, Current Financial Assets	136,737	18.8%	163,186	21.9%	115,065	16.4%	103,168	14.5%	88,235	13.1%
Accounts Receivable	79,307	10.9%	82,841	11.1%	64,743	9.2%	78,814	11.1%	87,108	12.9%
Inventory	167,458	23.0%	152,211	20.4%	152,882	21.7%	154,768	21.7%	149,710	22.1%
Property, plant and equipment	305,679	42.0%	314,337	42.1%	341,372	48.5%	348,813	49.0%	331,395	49.0%
Total Assets	$728,396	100.0%	$746,821	100.0%	$703,685	100.0%	$712,393	100.0%	$675,923	100.0%
Accounts Payable	113,693	15.6%	153,717	20.6%	97,893	13.9%	163,577	23.0%	152,487	22.6%
Current Liabilities	164,563	22.6%	208,076	27.9%	146,759	20.9%	207,227	29.1%	197,219	29.2%
Total Liabilities	282,679	38.8%	308,909	41.4%	261,605	37.2%	316,573	44.4%	317,493	47.0%
Total Shareholders' Equity	445,717	61.2%	437,912	58.6%	442,080	62.8%	395,820	55.6%	358,430	53.0%
Key Indices										
Debt Ratio	38.8%		41.4%		37.2%		44.4%		47.0%	
Current Ratio	246.9%		201.6%		238.3%		165.8%		170.9%	
Quick Ratio	136.7%		121.7%		134.2%		91.1%		95.0%	

Semiconductor market outlook and company strategic plans

Equipment forecast (short to mid term)



	2023	2024F	2025F	2026F
A&P Equipment	4.03	4.94	5.73	7.07
Test Equipment	6.27	7.14	8.18	9.71
Wafer Fab Equipment	95.61	100.75	107.56	122.64

Source: SEMI Equipment Market Data Subscription (EMDS), December 2024

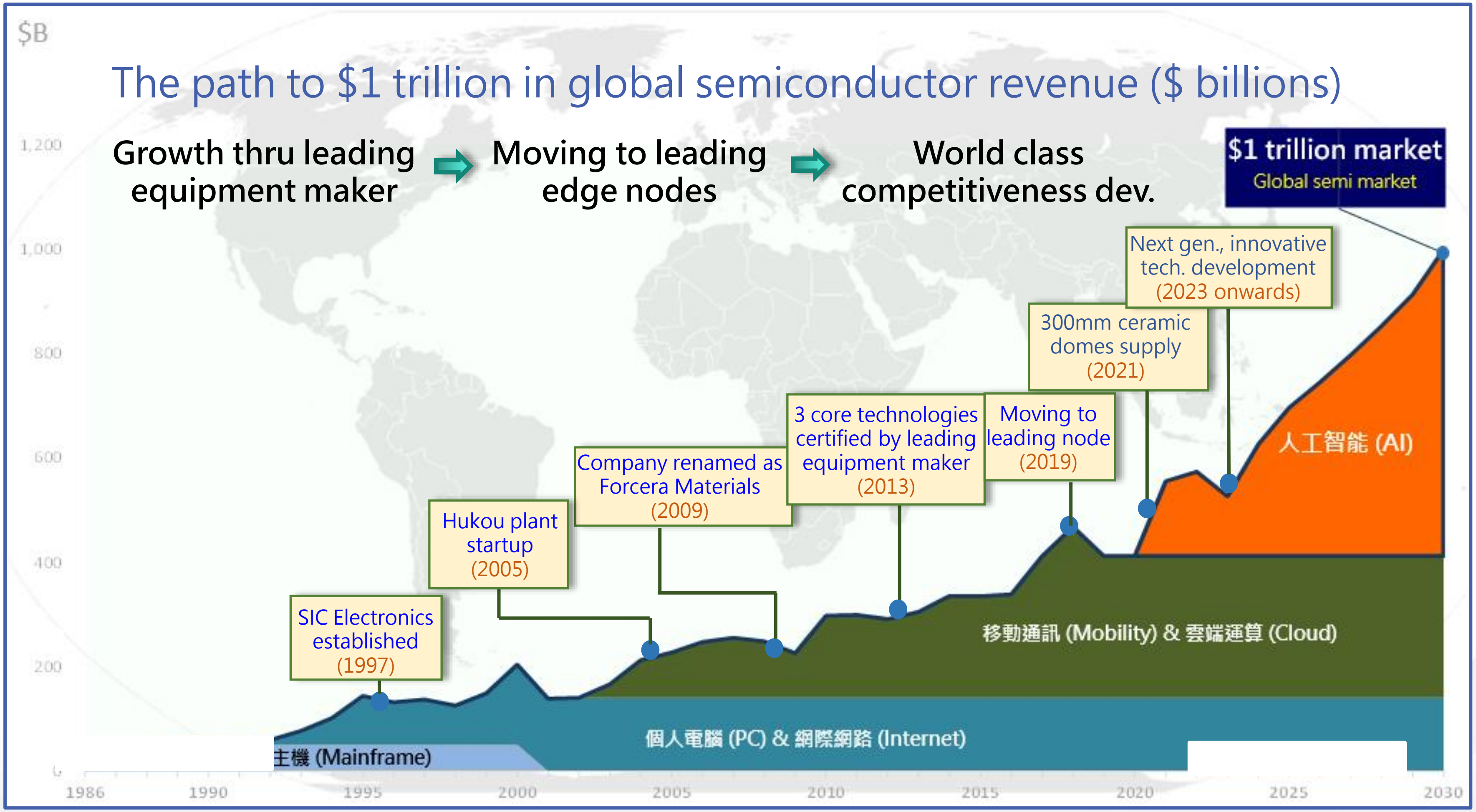
Global sales of total semiconductor manufacturing equipment are projected to grow 6.5% in 2024

- WFE (wafer fab equipment): to grow 5.4%
- Test (test equipment): to increase 13.8%
- A&P (assembly & packaging): to rebound by 22.6%

Equipment forecast to grow 7.1% in 2025

- Global semiconductor manufacturing equipment growth is expected to continue in 2025 and 2026

Global semiconductor market outlook



Source: Forcera analysis and extrapolation based on data from World Semiconductor Trade Statistics

Strategic plans

To develop global competitiveness by implementing strategic plans in a proactive way

- **Strategic plans**
  - ✓ Vertical extension (innovative tech., leading node)
  - ✓ Horizontal proliferation (semi value chain, new opportunities)

Next gen., innovative ceramic material development

Higher % share of leading node parts

Part refurb. capability development

New, advanced part clean line establishment

- **Core competence**
  - ✓ Leading edge nodes
  - ✓ Collaboration with leading companies

One of the select few company with semi grade ceramic material development capability

Capability for leading edge nodes
- ✓ micro/deep drilling
- ✓ surface treatment

Certified by world leading equipment maker

- **Core technologies**
  - ✓ 3 core technologies integration
  - ✓ OEM certified

Ceramic material processing → Precision machining & surface treatment → Part clean, etching

ESG performance

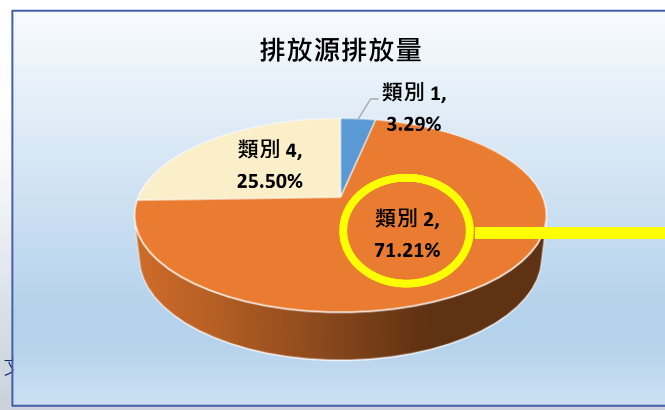
Carbon footprint verification

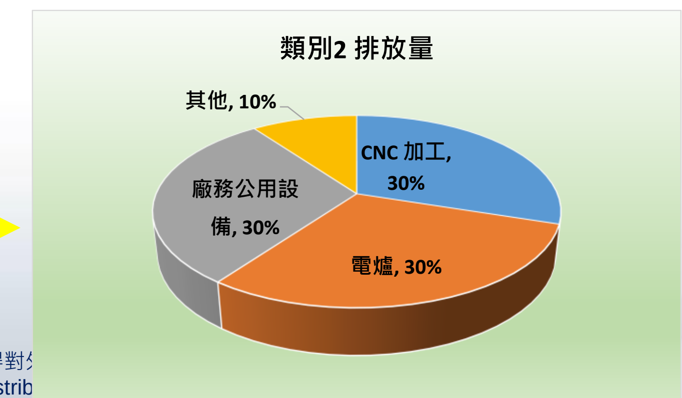
- 率先於**2022完成全廠區各類別排放源之排放量盤查** vs. **法規2026**之要求
- 自**2022年度起已建置碳排量盤查系統**，以科學化、系統化、智慧化等彙整廠內各項排放源之數量進行統計、分析以做為公司推動淨零碳排政策目標

各類別排放源排放量

類別	類別1				類別2	類別4	總排放當量
	固定燃燒 註1	移動燃燒 註2	製程排放	逸散排放 註3	外購電力 註4	組織使用產品間接排放 註5	
排放當量 (公噸CO_2e)	151.4498				3,281.2065	1,175.0712	4,607.728
	65.5956	15.0899	0.0000	70.7643			
占比 (%)	3.29%				71.21%	25.50%	100%
	1.42%	0.33%	0.00%	1.54%			

註1: 發電機 **註2:** 公務車、貨車 **註3:** 冷氣機、冰箱、製冷飲水機、除濕機、冰水機、汽車空調、空壓機台冷乾機、化糞池、滅火器
註4: 台電 **註5:** 購買原物料、廢棄物處置及清運





Social engagement

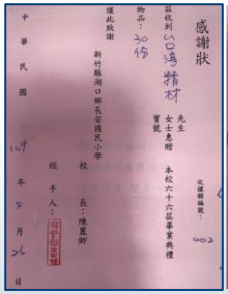
- Certificate of appreciation by school for educational activity support

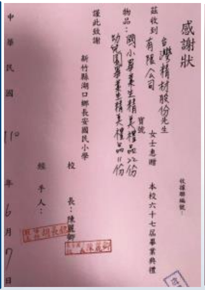
新竹縣湖口鄉長安國民小學
Hsin-chu County Chang-an Elementary School

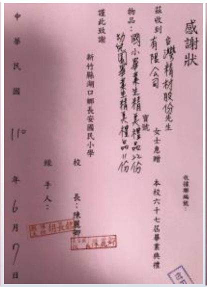

謹訂於中華民國113年6月12日(星期三)
上午9時整於本校多功能活動中心舉行
第70屆暨附設幼兒園第18屆畢業典禮
恭請
蒞臨指導
新竹縣長安國民小學
校　長 張小萍
家長會長 魏宏娸
敬邀
活動時間
09:00-11:30 畢業典禮
11:30-11:50 歡送畢業生離校

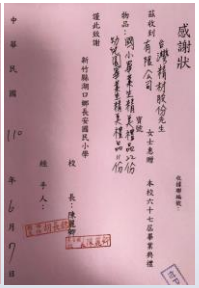

謹訂於中華民國112年6月14日(星期三)
上午9時整於本校多功能活動中心舉行
第69屆暨附設幼兒園第17屆畢業典禮
恭請
蒞臨指導
新竹縣長安國民小學
校　長 張小萍
家長會長 魏宏娸
敬邀
活動時間
09:00-11:00 畢業典禮
11:30-11:40 歡送畢業生離校

歷年感謝狀:

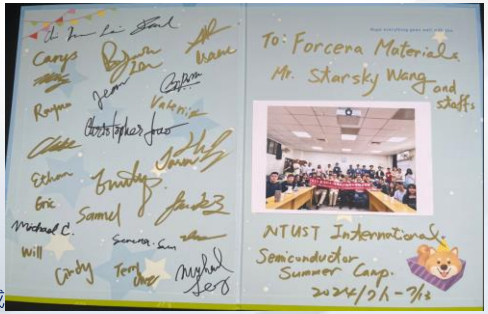




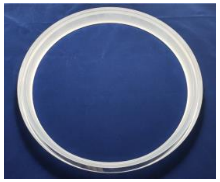
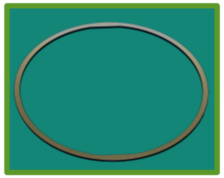
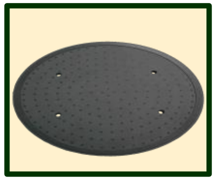




- Supporting international semiconductor summer camp
  - helped to develop talents in semiconductor industry
  - enhanced Forcera's visibility in international society




Forcera Materials Co., Ltd.
台灣精材股份有限公司


Thank you